

In the Specification:

Please amend the paragraph beginning on page 8, line 16, as follows:

The electrode pads 4, 6 on the wafer substrate 2 are electrically coupled to the electrode pads 7, 9 on the flexible printed board 30 through the wires 5, 8, respectively. The wires 5 are wired to the electrode pads 4 and the electrode pads 7 ~~through~~ through use of the wire bonding and also the wires 8 are wired to the electrode pads 6 and the electrode pads 9 through use of the wire bonding. At the time of the wiring, when the area of each of the electrode pads is narrow, there arises a problem that the efficiency of the wiring procedure is degraded and the coupling failure etc. is likely ~~occurred~~ to occur. However, as described above, according to the invention, since the area of each of the electrode pads 4, 6, 7, 9 can be formed larger, the efficiency of such bonding procedure can be improved and the failure ratio such as coupling failure etc. can be reduced.